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FOR IMMEDIATE RELEASE

ISSYS Receives Phase II SBIR Grant from NSF for Development of Wafer-Scale, Hermetic, Hybrid Integration of MEMS and Electronics

Integrated Sensing Systems, Inc. (ISSYS) Ypsilanti, MI announced that it has received a Phase II Small Business Innovation Research contract from the National Science Foundation (NSF). The 2-year project, titled "Wafer-Scale, Hermetic, Packaging of MEMS-Based Systems" is aimed towards development of a novel packaging method which will greatly simplify the packaging of MEMS and their associated electronics.

Dr. Nader Najafi, President/CEO of ISSYS, stated "this technology is highly enabling for commercialization of viable MEMS products. The practical hermetic integration of electronics and MEMS devices allows the commercialization of a variety of MEMS-based products that are currently not possible due to high cost of manufacturing or packaging problems. ISSYS' method can be used for a wide variety of devices, in particular, for applications where the MEMS device needs to be in direct contact with the media and the electronics need to be isolated from the environment." ISSYS' immediate products benefiting from this technology include intelligent catheters, and implantable intracranial pressure (ICP) monitors for traumatic brain injury (TBI) and intelligent shunts for hydrocephalus. Other potential applications include industrial, analytical, defense, safety, or biohazard detection applications.

Ms. Sonbol Massoud-Ansari, project's Principal Investigator/Vice President of ISSYS, stated, "We greatly appreciate the support from NSF, which will allow us to expedite the development of this novel packaging solution. We are very excited about developing this technology for our internal products as well as offering a flexible packaging platform to customers through our foundry service division. We plan to offer two packaging platforms, for both wired and wireless sensors, which will meet the need for a low-cost, robust manufacturing packaging solution."

Company Background: ISSYS is a leader in advanced MEMS technologies for medical devices, microfluidic and scientific analytical sensing applications. Founded in 1995, ISSYS is one of the oldest independent MEMS companies in the US. ISSYS operates a "full manufacturing under one roof," multi-million-dollar, state-of-the-art MEMS fabrication facility located near Ann Arbor, Michigan. An ISO 9001:2000 certified and ISO 13485:2003 qualified organization, ISSYS is a vertically integrated company dedicated to developing and manufacturing system-level products based on MEMS technology (MEMS Inside). Please visit <http://www.mems-issys.com/>

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